

FP0705

High frequency, high current power inductors



Applications

- Multi-phase and Vcore regulators
- Voltage Regulator Modules (VRMs)
 - Server and desktop
 - Central processing unit (CPU)
 - Graphics processing unit (GPU)
 - Application specific integrated circuit (ASIC)
 - High power density
- Data networking and storage systems
- Graphics cards and battery power systems
- Portable electronics
- Point-of-Load modules

Product description

- High current carrying capacity
- Low core loss
- Inductance Range from 72 nH to 220 nH
- Current range from 20 A to 65 A
- 7.0 mm x 7.0 mm footprint surface mount package in a 4.95 mm height
- Ferrite core material
- Halogen free, lead free, RoHS compliant

Environmental data

- Storage temperature range (Component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant



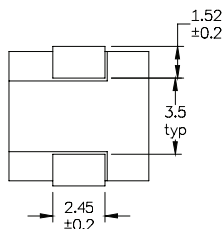
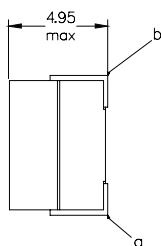
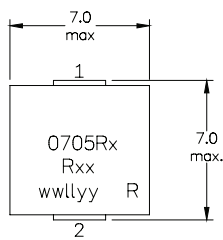
Product specifications

Part Number ⁷	OCL ¹ (nH) ±10%	FLL ² (nH) minimum	I _{rms} ³ (A)	I _{sat} 1 ⁴ (A)	I _{sat} 2 ⁵ (A)	DCR (mΩ) @ 20°C	K-factor ⁶
R1 version							
FP0705R1-R07-R	72	51	43	65	50	0.25 ± 10%	826
FP0705R1-R10-R	105	78	43	44	34	0.25 ± 10%	826
FP0705R1-R12-R	120	86	43	37	30	0.25 ± 10%	826
FP0705R1-R15-R	150	108	43	30	24	0.25 ± 10%	826
FP0705R1-R18-R	180	130	43	25	20	0.25 ± 10%	826
FP0705R1-R22-R	226	159	43	20	16	0.25 ± 10%	826
R2 version							
FP0705R2-R07-R	72	51	38	65	50	0.32 ± 9.4%	826
FP0705R2-R10-R	105	78	38	44	34	0.32 ± 9.4%	826
FP0705R2-R12-R	120	86	38	37	30	0.32 ± 9.4%	826
FP0705R2-R15-R	150	108	38	30	24	0.32 ± 9.4%	826
FP0705R2-R18-R	180	130	38	25	20	0.32 ± 9.4%	826
FP0705R2-R22-R	226	159	38	20	16	0.32 ± 9.4%	826
R3 version							
FP0705R3-R07-R	72	51	32	65	50	0.46 ± 6.5%	826
FP0705R3-R10-R	105	78	32	44	34	0.46 ± 6.5%	826
FP0705R3-R12-R	120	86	32	37	30	0.46 ± 6.5%	826
FP0705R3-R15-R	150	108	32	30	24	0.46 ± 6.5%	826
FP0705R3-R18-R	180	130	32	25	20	0.46 ± 6.5%	826
FP0705R3-R22-R	226	159	32	20	16	0.46 ± 6.5%	826

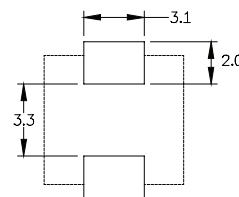
- Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc, +25 °C
- Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.1 Vrms, I_{sat}1, +25 °C
- I_{rms}: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125 °C under worst case operating conditions verified in the end application.
- I_{sat}1: Peak current for approximately 20% rolloff @ +25 °C
- I_{sat}2: Peak current for approximately 20% rolloff @ +125 °C

- K-factor: Used to determine B_{pp} for core loss (see graph).
B_{pp} = K * L * ΔI * 10⁻³. B_{pp} (Gauss), K: (K-factor from table),
L: (Inductance in nH), ΔI (Peak to peak ripple current in Amps).
- Part Number Definition: FP0705Rx-Rxx-R
FP0705= Product code and size
Rx= Version indicator
-Rxx= Inductance value in μH, R= decimal point
-R suffix = RoHS compliant

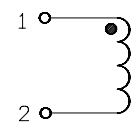
Dimensions (mm)



Recommended Pad Layout



Schematic



Part marking: 0705Rx (Rx = version indicator), Rxx = Inductance value in μH, R = decimal point, wwllly = date code, R = revision level

Tolerances are ±0.25 millimeters unless stated otherwise

PCB tolerances are ±0.1 millimeters unless stated otherwise

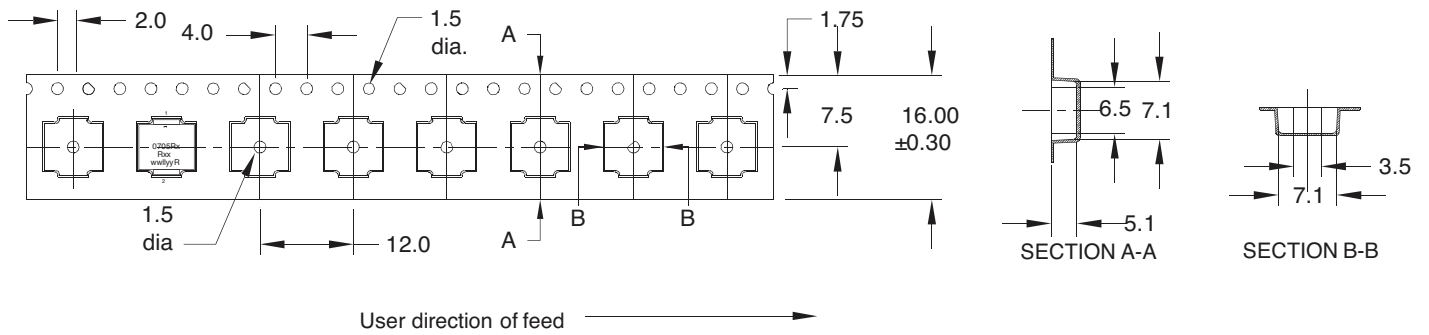
All soldering surface to be coplanar within 0.1016 millimeters

DCR measured between point "a" and point "b"

Do not route traces or vias underneath the inductor

Packaging information (mm)

Supplied in tape and reel packaging , 950 parts per 13" diameter reel



Temperature rise vs. total loss



Core loss vs. B_{p-p}



Inductance characteristics



Solder reflow profile



Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton
Electronics Division
 1000 Eaton Boulevard
 Cleveland, OH 44122
 United States
 www.eaton.com/elx

© 2016 Eaton
 All Rights Reserved
 Printed in USA
 Publication No. 4325 BU-SB08210
 January 2016

Eaton is a registered trademark.
 All other trademarks are property of their respective owners.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.